

Structure of Heat Slug-Equipped Packages
and the Packaging Method of The Same

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U.S. Appln. No. Unknown

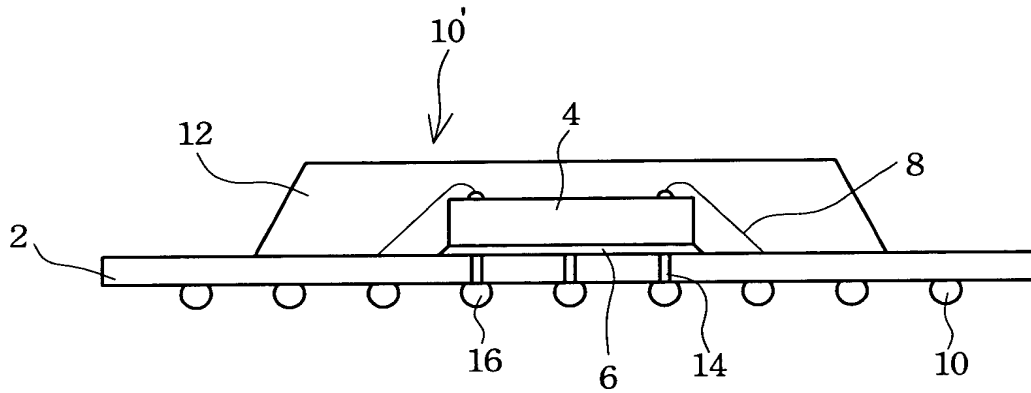


Fig. 1

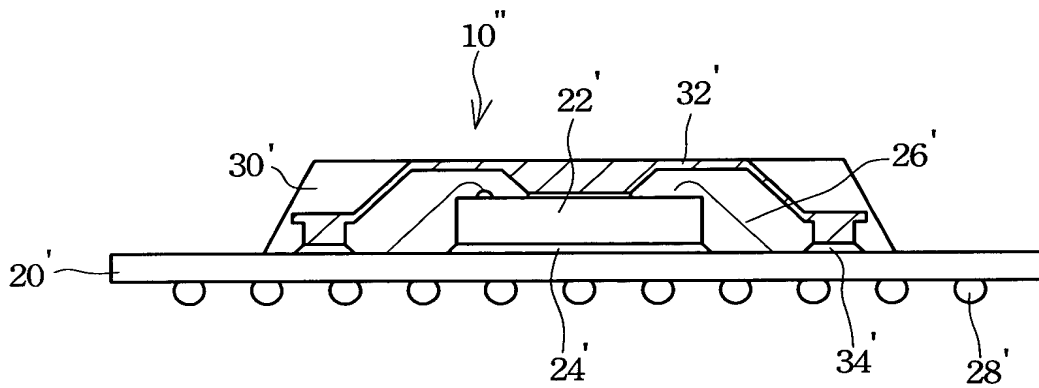


Fig. 2

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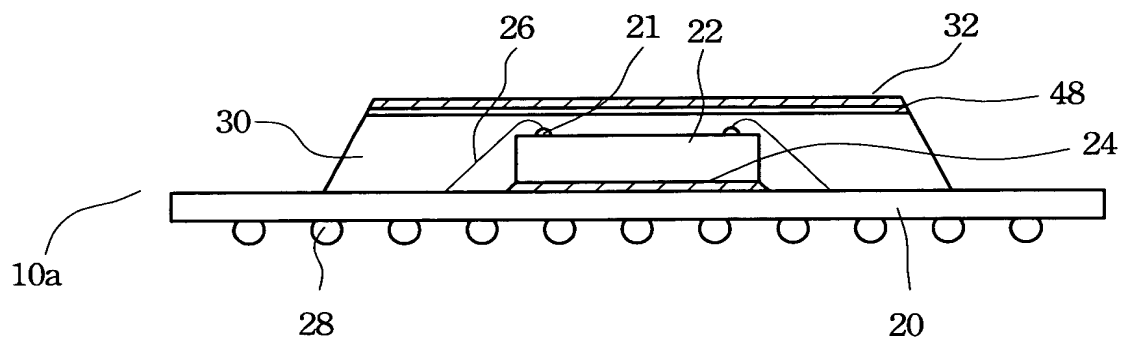


Fig. 3

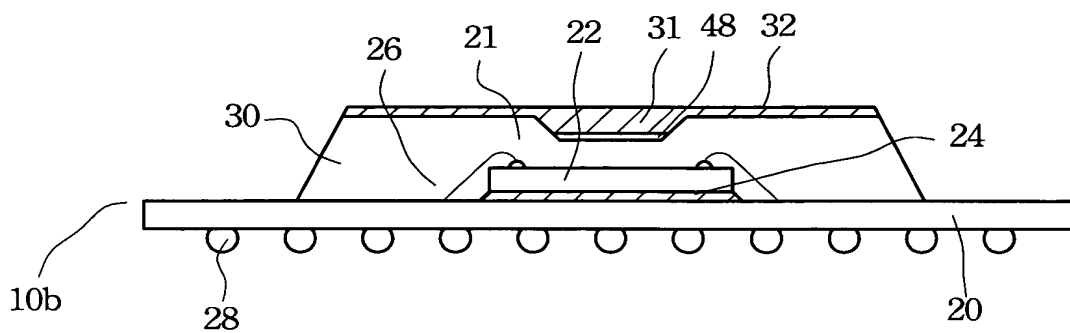


Fig. 4

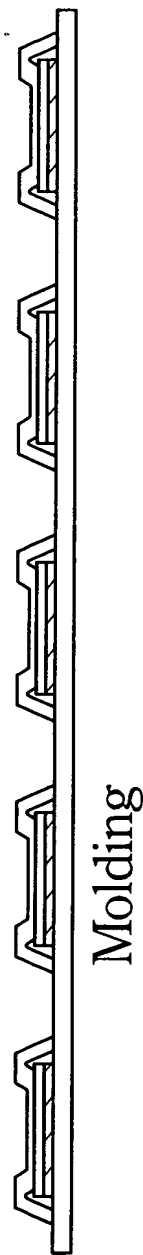
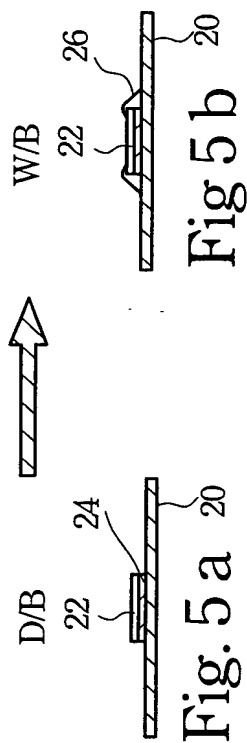


Fig. 5 c

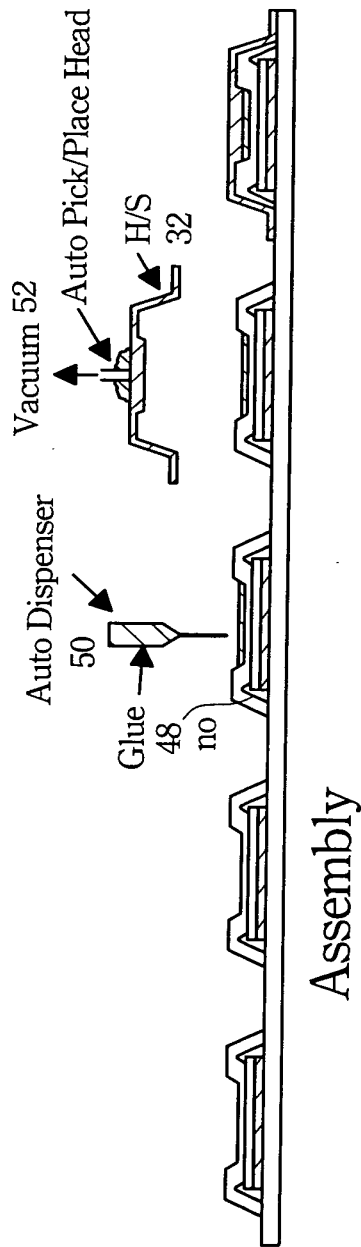


Fig. 5 d

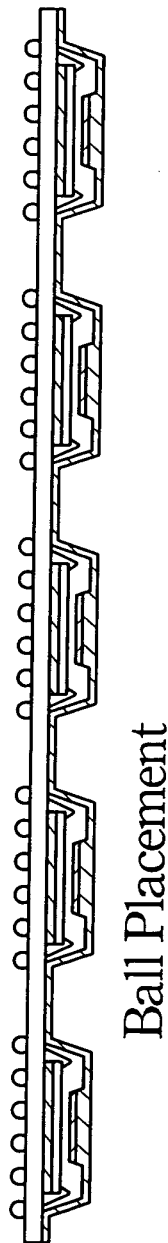
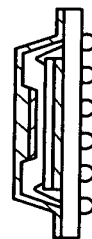


Fig. 5 e



Singulation

Fig. 5 f